

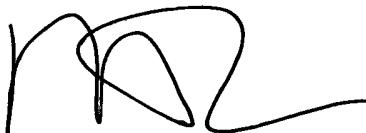
*P24*  
15. An article of manufacture comprising a microelectronic wafer substrate or flat panel display substrate having coated thereon a layer of the photoresist composition of any one of claim 1.

#### REMARKS

The specification has been amended to include the priority claim. For the sole purpose of reducing initial filing fees, claims 13-14 and 17-25 have been cancelled without prejudice, and claims 3, 5-12 and 15 have been amended to eliminate multiple dependencies.

Early consideration and allowance of the application are solicited.

Respectfully submitted,



Peter F. Corless (Reg. 33,860)  
EDWARDS & ANGELL, LLP  
*Dike, Bronstein, Roberts & Cushman IP Group*  
P.O. Box 9169  
Boston, MA 02209  
(617) 523-3400

**VERSION WITH CHANGES MARKED**

3. (amended) A photoresist of claim 1 [or 2] wherein the resin comprises photoacid-labile groups.

5. (amended) A photoresist of claim 2 [or 3] wherein the resin comprises a photoacid-labile ester group.

6. (amended) A photoresist of claim 1 [any one of claims 1 through 5] wherein the resin comprises a polymerized cyclic olefin.

7. (amended) A photoresist of claim 1 [any one of claims 1 through 6] wherein the resin comprises a polymerized monomer comprising ethylene unsaturated carbonyl or di-carbonyl.

8. (amended) A photoresist of claim 1 [any one of claims 1 through 7] wherein the resin is a terpolymer.

9. (amended) A photoresist of any one of claim 1 [claims 1 through 8] wherein the resin is a tetrapolymer.

10. (amended) The photoresist of claim 1 [any one of claims 1 through 9] wherein the polymer further comprises one or more units selected from the group consisting of an acid; nitrile; an anhydride; a lactone; or a photoacid labile group that contains a leaving group that has other than an alicyclic moiety.

11. (amended) The photoresist of claim 1 [any one of claims 1 through 11] wherein the polymer is substantially of aromatic groups.

12. (amended) A method of forming a positive photoresist relief image, comprising:

- (a) applying a coating layer of a photoresist of claim 1 [any one of claims 1 through 11] on a substrate; and
- (b) exposing and developing the photoresist layer to yield a relief image.

15. An article of manufacture comprising a microelectronic wafer substrate or flat panel display substrate having coated thereon a layer of the photoresist composition of any one of claim 1 [claims 1 through 11].